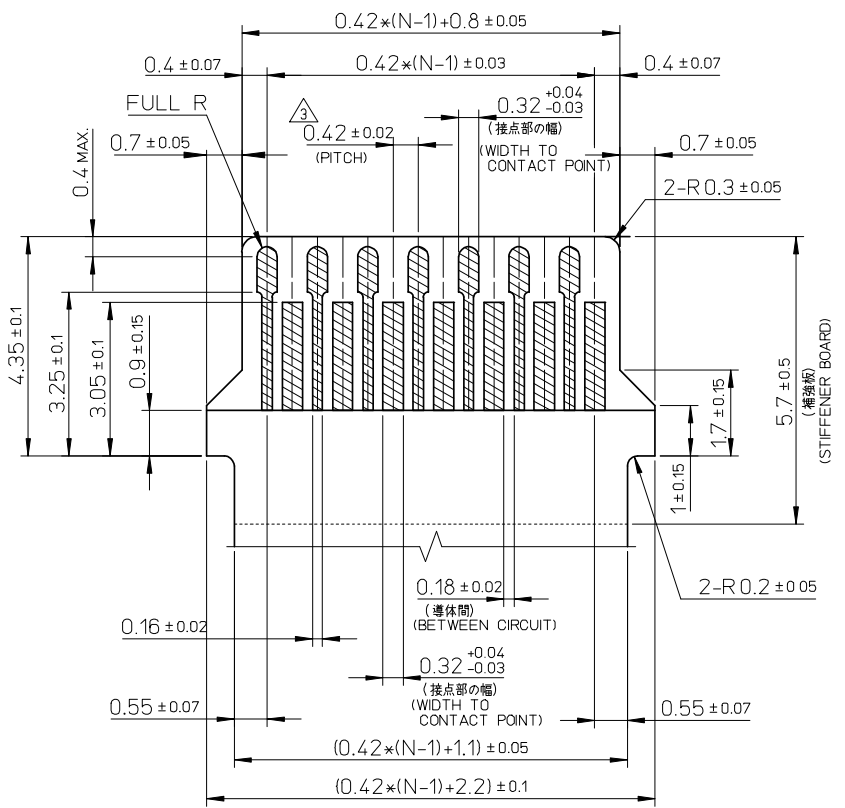


502555-1360	502555-1369	136
EMBOSSD TAPE		CIRCUIT
ORDER NO. オーダー番号		MATERIAL NO.

RELEASED EC NO: J2008-4046 DRW: K.MURAKAMI 2008/05/28 CHKD: K.TAKAHASHI 2008/05/28 APPR: K.TAKAHASHI 2008/05/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.3	DRAWN BY K. MURAKAMI	DATE 2008/05/27	TITLE 0.42 FPC CONN HSG ASSY UPR CONT WITH DUSTCOVER		
	10 OVER 30 UNDER	± 0.3	CHECKED BY K. TAKAHASHI	DATE 2008/05/27	MOLEX INCORPORATED		
	30 OVER	± 0.3	APPROVED BY H. HIRATA	DATE 2008/05/27	DOCUMENT NO. SD-502555-001		
	ANGULAR ±1°		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 3		
A	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



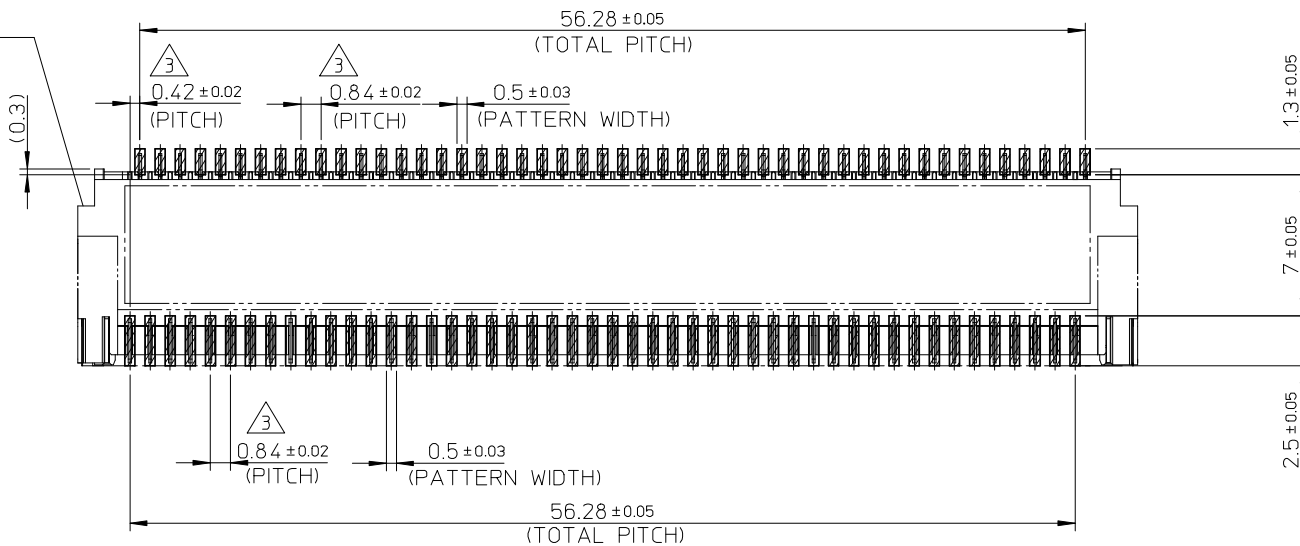
FPCについて：
 抜き方向は、導体側から補強板側を推奨致します。
 補強フィルム材質は、ポリイミドを推奨致します。
 接着剤は熱硬化接着剤を推奨致します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、
 染み出しが無い様、お願い致します。

ABOUT FPC:
 RECOMMENDED PUNCHER DIRECTION:
 FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
 RECOMMENDED MATERIAL:
 STIFFENER FILM : POLYIMIDE
 BONDING AGENT : THERMOSETTING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE
 CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE
 THE DEFECT IN ELECTRICAL CONTINUITY.

適合FPC推奨寸法
 APPLICABLE FPC
 RECOMMENDED DIMENSION
 (仕上がり厚さ : 0.3±0.05)
 (THICKNESS : 0.3±0.05)

RELEASED EC NO: J2008-4046 DRWN: K. MURAKAMI 2008/05/28 CHKD: K. TAKAHASHI 2008/05/28 APPR: K. TAKAHASHI 2008/05/29	DESCRIPTION REV: A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.3	DRAWN BY K. MURAKAMI	DATE 2008/05/27	TITLE 0.42 FPC CONN HSG ASSY UPR CONT WITH DUSTCOVER				
		10 OVER 30 UNDER	±0.3	CHECKED BY K. TAKAHASHI	DATE 2008/05/27	MATERIAL NO. SD-502555-001				
		30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 2008/05/27	SHEET NO. 2 OF 3				
		ANGULAR ±1°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		MOLEX INCORPORATED		

コネクタ位置
CONNECTOR POSITION



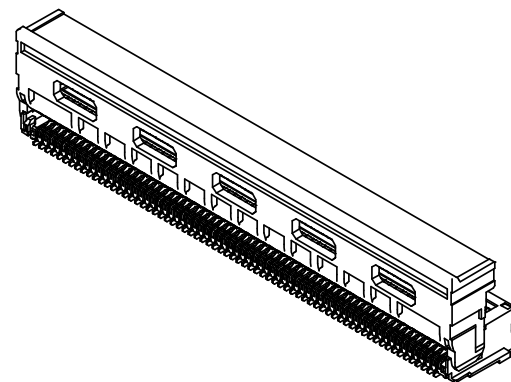
参考基板レイアウト図
RECOMMENDED P.C.BOARD
PATTERN DIM(REF)

(マウント面)
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATERIAL
ハウジング: 液晶ポリマー ガラス充填 UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0
- アクチュエータ: PPS、ガラス充填 UL94V-0
ACTUATOR: POLYPHENYLENESULFIDE (GLASS FILLED) UL94V-0
- ターミナル: リン青銅 (±0.15)
TERMINAL: PHOSPHOR-BRONZE
- メッキ
PLATING
- コンタクト: ニッケル下地
CONTACT AREA: GOLD(0.1 MICROMETER MIN. FOR SEALING DEPOSITION) OVER NICKEL PLATING
- テール: ニッケル下地
TAIL AREA: GOLD(0.05 MICROMETER MIN. FOR SEALING DEPOSITION) OVER NICKEL PLATING

4. そり/ねじれ調整により、外観形状が変更することがあります。外形寸法が変更する場合は、別途協議させていただきます。
THE EXTERNALS SHAPE CHANGES BY WARP/TWIST ADJUSTMENT OCCASIONALLY. WE WILL CONFER SEPARATELY WHEN EXTERNALS SIZE CHANGES.
5. 推奨ペースト厚: 150µm
RECOMMEND SCREEN THICKNESS : 150µm
6. ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT



△. ソルダータール半田付け面のズレ量は、基準面 Y に対し、上方向 0.05 MAXIMUM、下方向 0.25 MAXIMUM とする。又、相互のパラッキ量は、0.1 MAXIMUM とする。
MISALIGNMENT OF SOLDER TAILS FROM Y UPPER DIRECTION : 0.05 MAXIMUM, LOWER DIRECTION : 0.25 MAX. OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAX.

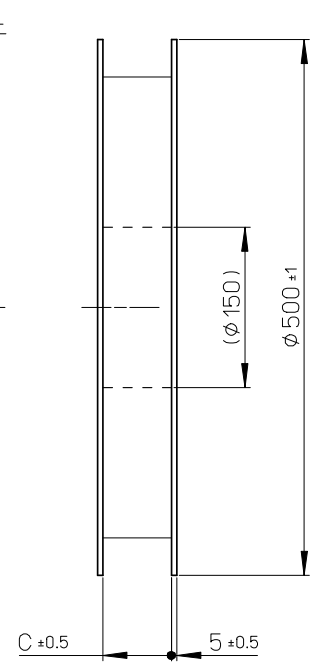
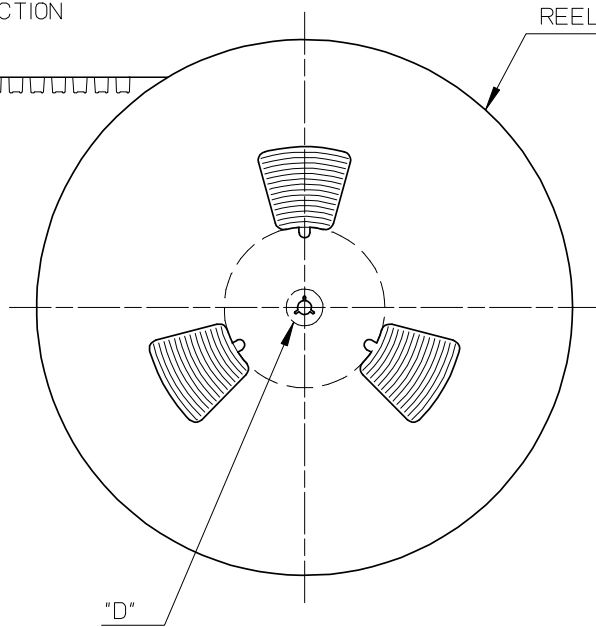
△. 公差非累積のこと。
NON-ACCUMULATIVE.

RELEASED EC NO: J2008-4046 DRW: K. MURAKAMI 2008/05/28 CHKD: K. TAKAHASHI 2008/05/28 APPR: K. TAKAHASHI 2008/05/29	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE --#	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.3	DRAWN BY K. MURAKAMI	DATE 2008/05/27	TITLE 0.42 FPC CONN HSG ASSY UPR CONT WITH DUSTCOVER			
		10 OVER 30 UNDER	±0.3	CHECKED BY K. TAKAHASHI	DATE 2008/05/27				
		30 OVER	±0.3	APPROVED BY H. HIRATA	DATE 2008/05/27	MOLEX INCORPORATED			
A	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		MATERIAL NO.	DOCUMENT NO. SD-502555-001	SHEET NO. 3 OF 3	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

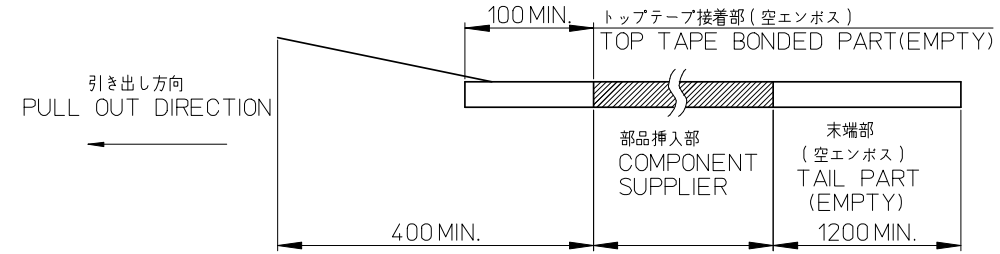
NOTES

- 製品詳細寸法については図面 SD-502555-001を参照下さい。
RE DETAILED DIMENSION, SEE SD-502555-001
- 梱包数量: 500 個/リール
NUMBER OF CONNECTORS: 500 PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH

引き出し方向
PULL OUT DIRECTION

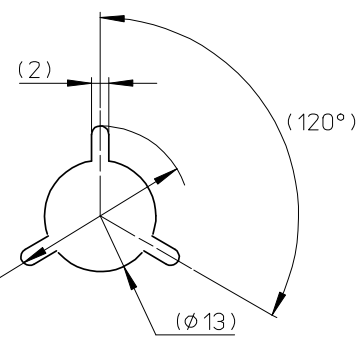


トップテープ未接着部
TOP TAPE NON-BONDED PART



- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE): ポリプロピレン
POLYPROPYLENE
トップテープ(TOP TAPE): PET, PE
リール(REEL): 紙製
PAPER

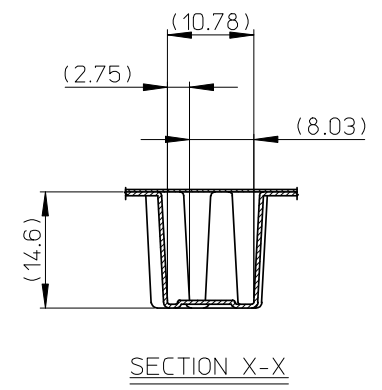
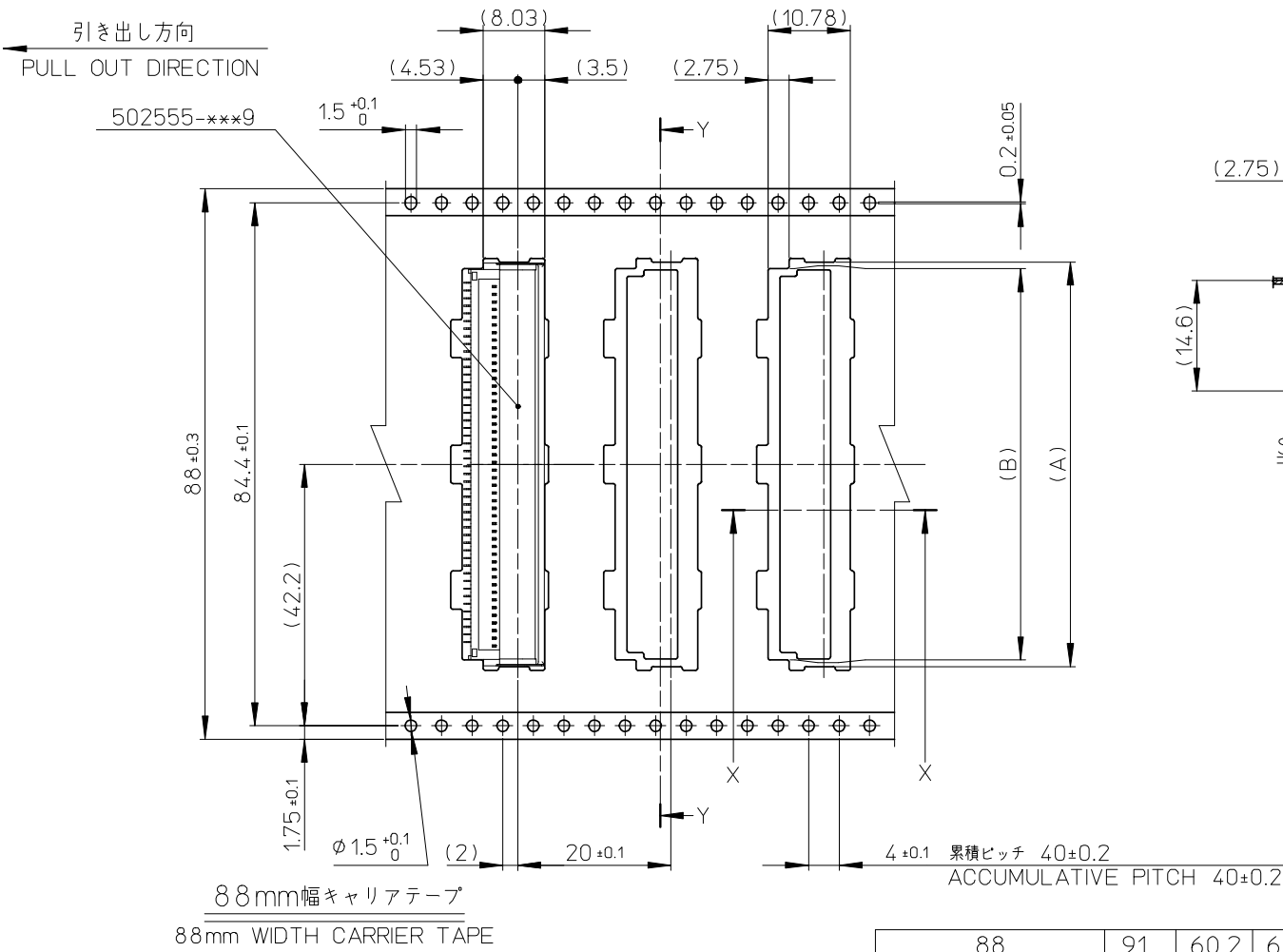
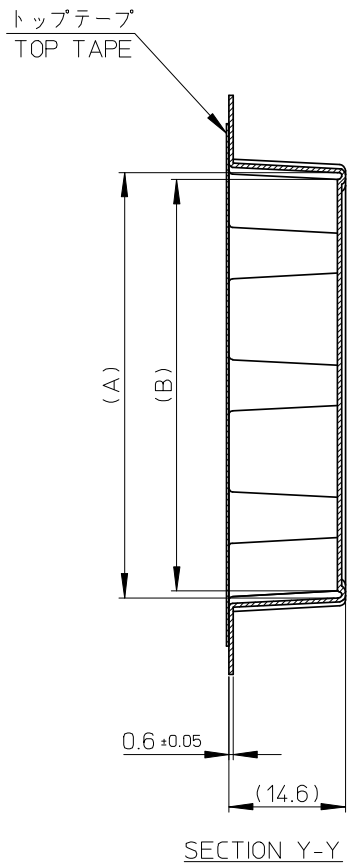
- ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT



DETAIL "D"

MODEL NO. 502555-***0

RELEASED EC NO: J2008-4046 DRWN:KOMURAKAMI 2008/05/28 CH'KD:TAKAHASHI 2008/05/28 APPR:KATAHASHI 2008/05/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY K. MURAKAMI	DATE 2008/05/27	TITLE 0.42 FPC CONN EO HSG ASSY UPR CONT WITH DUSTCOVER EMBSTP PKG			
	10 OVER 30 UNDER	± ---	CHECKED BY K. TAKAHASHI	DATE 2008/05/27				
	30 OVER	± ---	APPROVED BY H. HIRATA	DATE 2008/05/27	MOLEX INCORPORATED			
	ANGULAR	± --- °	MATERIAL NO. SEE SHEET 2 OF 2					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



88	91	60.2	61.9	502555-1360	136
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No	極数 Ckt

RELEASED EC NO: J2008-4046 DRWN:KOMURAKAMI 2008/05/28 CHK:KOTAKAHASHI 2008/05/28 APPR:KTAKAHASHI 2008/05/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY K. TAKAHASHI	DATE 2008/05/27	TITLE 0.42 FPC CONN EO HSG ASSY UPR CONT WITH DUSTCOVER EMBSTP PKG		
	10 OVER 30 UNDER	± ---	CHECKED BY K. TAKAHASHI	DATE 2008/05/27	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY H. HIRATA	DATE 2008/05/27	MATERIAL NO.	DOCUMENT NO.	SHEET NO.
	ANGULAR	± --- °	SEE CHART		SD-502555-002	2 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					